

VDE Prüf- und Zertifizierungsinstitut GmbH • Merianstr. 28 • 63069 Offenbach

Texas Instruments Inc.
12500 Texas Instruments Blvd.
Mr Sanjay Singh
M/S A3000
DALLAS TX 75243
USA2

Offenbach, 2025-03-10

Your ref.	Your letter	Our ref. - please indicate	Contact
Sanjay Singh	2025-03-01	5005845-4520-0001/327769 TL2/swa	Mr. Schwab Tel +49 69 8306 607 Fax +49 69 8306 606 ralf.schwab@vde.com

Translation: In any case the German version shall prevail

PR Ü F B E R I C H T
zur Information des Auftraggebers
Test Report for the Information of the applicant

Produkt / Product:

Mikrokontroller Selbstdiagnose Bibliothek.
Microcontroller self-diagnostic library package

Version: 5.00.01

For Microcontroller device families

F280013x, F280015x, F28002x, F28003x, F28004x, F2838x, F28P55x, F28P65x

Dear Sirs,

dieser Prüfbericht enthält das Ergebnis einer einmaligen Untersuchung an dem zur Prüfung vorgelegten Erzeugnis. Ein Muster dieses Erzeugnisses wurde geprüft, um die Übereinstimmung mit den nachfolgend aufgeführten Normen bzw. Abschnitten von Normen festzustellen. Die Prüfung wurde durchgeführt vom 2025-02-24 bis 2025-03-12.

This test report contains the result of a singular investigation carried out on the product submitted. A sample of this product was tested to found the accordance with the thereafter listed standards or clauses of standards resp. The testing was carried out from 2025-02-24 to 2025-03-12.

Der Prüfbericht berechtigt Sie nicht zur Benutzung eines Zertifizierungszeichens des VDE und berücksichtigt ausschließlich die Anforderungen der unten genannten Regelwerke.

The test report does not entitle for the use of a VDE Certification Mark and considers solely the requirements of the specifications mentioned below.

Wenn gegenüber Dritten auf diesen Prüfbericht Bezug genommen wird, muss dieser Prüfbericht in voller Länge an gleicher Stelle verfügbar gemacht werden.

Whenever reference is made to this test report towards third party, this test report shall be made available on the very spot in full length.

REMARK: VDE DETAIL TESTREPORT REFERENCE: VDE 327769-TL2-1

I – ANGEWENDETE STANDARDS / STANDARDS APPLIED

DIN EN 60335-1 (VDE 0700-1):2024-07
EN 60335-1:2012+AC+A11+A13+A1+A2+A14-A16:2023
ANHANG R; KLASSE R1 und *R2
ANNEX R; CLASS R1 and *R2

IEC 60335-1:2020
ANHANG R; KLASSE R1 und *R2
ANNEX R; CLASS R1 and *R2

DIN EN 60730-1 (VDE 0631-1): 2021-06
ANHANG H; KLASSE B und *C
ANNEX H; CLASS B and *C

IEC 60730-1: 2022

WEITERHIN/FURTHERMORE

IEC 60730-1:2013
IEC 60730-1:2013/AMD1:2015
IEC 60730-1:2013/AMD2:2020
ANHANG H; KLASSE B und *C
ANNEX H; CLASS B and *C

ANMERKUNG: Die Anforderungen der Normenreihe 60730-1 Anhang H für Klasse B & C, Ausgabedaten 2022 und 2020 sind vergleichbar.

REMARK: The requirements of 60730-1 annex H for class B and C are comparable between the 60730-1 versions of 2020 and 2022.

ANMERKUNG: Die Anforderungen der Normenreihe 60730-1 Tabelle H für Klasse B & C und der 60335-1 Tabelle R1 für Klasse R1 & R2 sind vergleichbar.

REMARK: The requirements of 60730-1 table H for class B and C are comparable to table R1 of 60335-1 for class R1 and R2.

*Anmerkung: Manche Typen der Familie verfügen über Co-Prozessoren oder 2 Kerne. Hier kommt ein Lockstep Test zum Einsatz der Anforderungen einer Klasse C erfüllen kann. Weiterhin kann reziproker Vergleich genutzt werden.

*Remark: Some devices covered by this test report have co processors or 2 cores, for such devices a lockstep test was provided, which can fulfil requirements of class C. Furthermore reciprocal comparison can be used.

*Types complying with Class C measures.

F280015x; F28002x; F2838x; F28003x; F28004x; F28P55x; F28P65x.

II – SELBSTDIAGNOSE ROUTINEN / SELF-DIAGNOSTIC ROUTINES
ENGLISH DESCRIPTION ONLY

TABLE H.2 – MEASURES TO ADDRESS FAULT/ERRORS (Software Class B)			
Component	Fault/error	Declared measures	Verdict
1. CPU	-	-	-
1.1 Registers	Stuck at	Register Test	P
1.3 Program counter	Stuck at	*see remark 1 (watchdog timers may be used to supervise the program execution)	P
2. Interrupt handling and execution	No interrupt	*see remark 1 (watchdog timers may be used to supervise the interrupt execution)	P
	Too frequent interrupt	*see remark 1 (watchdog timers may be used to supervise the interrupt execution)	P
3. Clock	Wrong frequency (for quartz synchronized clock: harmonics/ sub-harmonics only)	Comparison of 2 timers. DCC (Dual clock comparator)	P
4. Memory	-	-	-
4.1 Invariable memory	All single bit faults	CRC32Bit Remark: Additional integrated measure (ECC) is available.	P
4.2 Variable memory	DC fault	March 13N Test Remark: Additional integrated measures like ECC or Parity are available.	P
4.3. Addressing (relevant to variable and invariable memory)	Stuck at	March 13N Test Remark: Additional integrated measures like ECC or Parity are available.	P
5. Internal data path	-	-	-
5.1 Data	Stuck at	With measures acc. to clause 4	P
5.2 Addressing	Wrong address	With measures acc. to clause 4	P
6. External communication	-	-	-

6.1 Data	Hamming distance 3		N/A
6.2 Addressing	Wrong address		N/A
6.3 Timing	Wrong point in time		N/A
	Wrong sequence		N/A
7. Input/output periphery	-	-	-
7.1 Digital I/O	Fault conditions specified in Cl.H.13		N/A
7.2 Analog I/O	-	-	-
7.2.1 A/D and D/A-convertor	Fault conditions specified in Cl. H.13		N/A
7.2.2 Analog multiplexer	Wrong addressing		N/A
9. Custom chips e.g. ASIC, GAL, gate array	Any output outside the static and dynamic functional specification		N/A

TABLE H.2 – MEASURES TO ADDRESS FAULT/ERRORS (Software Class C)			
Component	Fault/error	Declared measures	Verdict
1. CPU	-	-	-
1.1 Registers	DC fault	Lockstep & HW BIST Methodology. Reciprocal comparison.	P
1.2 Instruction decoding and execution	Wrong decoding and execution	Lockstep & HW BIST Methodology. Reciprocal comparison.	P
1.3 Program counter	DC fault	Lockstep & HW BIST Methodology. Reciprocal comparison.	P
1.4 Addressing	DC fault	Lockstep & HW BIST Methodology. Reciprocal comparison.	P
1.5 Data paths instruction decoding	DC fault	Lockstep & HW BIST Methodology. Reciprocal comparison.	P
	execution	Lockstep & HW BIST Methodology. Reciprocal comparison.	P

2. Interrupt handling and execution	No interrupt	Lockstep & HW BIST Methodology. Reciprocal comparison.	P
	Too frequent interrupt related to different sources	Lockstep & HW BIST Methodology. Reciprocal comparison.	P
3. Clock	Wrong frequency (for quartz synchronized clock: harmonics/ sub-harmonics only)	STL & HW BIST Reciprocal comparison. DCC (Dual clock comparator)	P
4. Memory	-	-	-
4.1 Invariable memory	99,6 % coverage of all information errors	Lockstep and reciprocal comparison. Reciprocal comparison Flash ECC.	P
4.2 Variable memory	DC fault	Lockstep and reciprocal comparison. Independent HW comparator	P
	Dynamic cross links	Lockstep and reciprocal comparison. Independent HW comparator	P
4.3 Addressing (relevant to variable and invariable memory)	DC fault	Lockstep and reciprocal comparison. Independent HW comparator	P
5. Internal data path	-	-	-
5.1 Data	DC fault	See clauses 4	P
5.2 Addressing	Wrong address	See clauses 4	P
	Multiple addressing	See clauses 4	P
6 External communication	-	-	-
6.1 Data	Hamming distance 4		N/A
6.2 Addressing	Wrong address		N/A
	Multiple addressing		N/A
6.3 Timing	Wrong point in time		N/A
	Wrong sequence		N/A

7. Input/output periphery	-	-	-
7.1 Digital I/O	Fault conditions specified in Cl.H.13		N/A
7.2 Analog I/O	-	-	-
7.2.1 A/D and D/A-converto	Fault conditions specified in Cl. H.13		N/A
7.2.2 Analog multiplexer	Wrong addressing		N/A
8. Monitoring devices and comparators	Any output outside the static and dynamic functional specification		N/A
9 Custom chips e.g. ASIC, GAL, gate array	Any output outside the static and dynamic functional specification		N/A

III – TESTMETHODIK / TEST METHODOLOGY

Die vorliegenden Dokumente nach 60335-1 und 60730-1 wurden einem Review unterzogen. Die vorgelegten Funktionen wurden unter Zuhilfenahme einer Testumgebung aus IN-CIRCUIT EMULATOR / DEBUGGER und einem Evaluation Board geprüft, Reviews / Prüfungen fanden am 2025-02-21, 2025-02-25, 2025-03-04 statt. Teilnehmende waren die maßgeblichen Entwickler der Fa. Texas Instruments und ein Experte des VDE Institutes.

The provided documents acc. to the requirements of 60335-1 / 60730-1 have been reviewed. The provided functions have been tested using the IN-CIRCUIT EMULATOR / DEBUGGER and an evaluation board during a review / witness test sessions dated 2025-02-21, 2025-02-25, 2025-03-04 participating development staff of Texas Instruments and an expert of VDE.

IV – ERGEBNIS / RESULT

Die unter II benannten Selbst-Diagnose-Routinen erfüllen die Anforderungen der unter I benannten Normen. Die unter II benannten Selbst-Diagnose-Routinen können zum Aufbau einer Selbst-Test-Bibliothek gemäß der unter I benannten Normen verwendet werden

The self-diagnostic routines mentioned under II fulfill the requirements of the standards mentioned under I. The self-diagnostic routines mentioned under II are suitable to be used to create a self-test library according the standards mentioned under I.

Anhang / Annex

Übersicht der Typen, die von diesem Testreport abgedeckt werden.

Overview of types covered by this test report.

Device comparison

	Technical Reference Manual	Safety Manual	stl_can_ram	stl_cpu_reg	stl_crc	stl_hwbist	stl_lcm	stl_march	stl_mcan_ram	stl_osc_ct	stl_osc_hr	stl_pie_ram	stl_sp
F280013x	link	link	X	X ¹	X ¹			X		X	X	X ²	X
F280015x*	link	link	X	X	X		X	X	X	X	X	X ²	X
F28002x	link	link	X	X	X	X		X		X	X	X	
F28004x	link	link	X	X	X			X		X	X	X	
F2838x	link	link	X	X ³	X	X ³		X	X	X	X	X	
F28003x	link	link	X	X	X	X		X	X	X	X	X	
F28P65x*	link	link	X	X ³	X	X ³	X	X	X	X	X	X	
F28P55x	link	link		X	X			X	X	X	X	X ²	

1. Device does not have VCU instruction set extension
2. Device has vector table parity instead of redundant PIE RAM comparison
3. Device has FPU64 instruction set extension (additional FPU registers)

Live links for the devices

	Technical Reference Manual	Safety Manual
F280013x	link	link
F280015x	link	link
F28002x	link	link
F28004x	link	link
F2838x	link	link
F28003x	link	link
F28P65x	link	link
F28P55x	link	link

File listing and hashes

F280013x SDL v5.00.01
 f280013x/include/stl_can_ram.h 6e681258023830d2862feb356f056fd5
 f280013x/include/stl_cpu_reg.h 66dfbe6d2f8ba19d5a6f23c2421b2e3b
 f280013x/include/stl_crc.h 31b74b897137ff16e8ab39594846e48b
 f280013x/include/stl_march.h 06579517c81f292238d77d17e0647b40
 f280013x/include/stl_osc_ct.h cca19730f28f9a68a003f048797961ea
 f280013x/include/stl_osc_hr.h ada6a5c5bc6e2f22db8e7853dde772e5
 f280013x/include/stl_pie_ram.h 55a8311ec0c3bcfc1396303f46366d82
 f280013x/include/stl_sp.h 5b31e4577a070977a709fde08d55957c
 f280013x/include/stl_util.h 0133093796289091aaef9e889fd7727a
 f280013x/source/stl_can_ram.c 10d1d759e590dce8ed6fe434b5247799
 f280013x/source/stl_cpu_reg.asm 7e3f1a640c1eca6baf9b3e306bbc8246
 f280013x/source/stl_crc.c 7ee331966a5b05d57fdb1459be964216
 f280013x/source/stl_march.c 76dff6833770cd06c2a883ab48c34ab0
 f280013x/source/stl_march_s.asm 1244aad667d6f9faa4e8aa74399fe7c8
 f280013x/source/stl_osc_ct.c b78b21ed19b69e18abc0f802e73d5e12
 f280013x/source/stl_osc_hr.c b3cab1259792c3139e8ce0b66ed53a87
 f280013x/source/stl_pie_ram.c 7e09c3816df19d81d7e90e839c9ea21f
 f280013x/source/stl_sp.c 30b0c5d62b45ba912f14ce44b832b46a
 f280013x/source/stl_util.c 2309934d20ae1759419fa96635fa1330

F280015x SDL v5.00.01
 f280015x/include/stl_can_ram.h 6e681258023830d2862feb356f056fd5
 f280015x/include/stl_cpu_reg.h ebd4a64d2c9e0e9de18d61c7e9966086
 f280015x/include/stl_crc.h a97561fa820eb9a4169bb2f0797e832b
 f280015x/include/stl_lcm.h 72a01fb20d2c66903fc4457d4698bea1
 f280015x/include/stl_march.h 06579517c81f292238d77d17e0647b40
 f280015x/include/stl_mcan_ram.h dc30db8672f86d3d61a767653851e315
 f280015x/include/stl_osc_ct.h cca19730f28f9a68a003f048797961ea
 f280015x/include/stl_osc_hr.h ada6a5c5bc6e2f22db8e7853dde772e5
 f280015x/include/stl_pie_ram.h 55a8311ec0c3bcfc1396303f46366d82
 f280015x/include/stl_sp.h 5b31e4577a070977a709fde08d55957c
 f280015x/include/stl_util.h 0e6f51e768a8726974ff6a3e5c02598f
 f280015x/source/stl_can_ram.c 10d1d759e590dce8ed6fe434b5247799
 f280015x/source/stl_cpu_reg.asm 14d8a30965a8aa1eee42cd6f8b5cd7a7
 f280015x/source/stl_crc.c 4e83e790250e43b89b0690c06b72d8fb
 f280015x/source/stl_crc_s.asm 296920111a7af3a9f84421f4f7c51b60
 f280015x/source/stl_lcm.c eb2a5c37d94766d0c2aa9ed5afd8a089
 f280015x/source/stl_march.c 76dff6833770cd06c2a883ab48c34ab0
 f280015x/source/stl_march_s.asm 1244aad667d6f9faa4e8aa74399fe7c8
 f280015x/source/stl_mcan_ram.c 6c4585e2a434f76e0b949283c4680982
 f280015x/source/stl_osc_ct.c b78b21ed19b69e18abc0f802e73d5e12
 f280015x/source/stl_osc_hr.c b3cab1259792c3139e8ce0b66ed53a87
 f280015x/source/stl_pie_ram.c 7e09c3816df19d81d7e90e839c9ea21f
 f280015x/source/stl_sp.c 30b0c5d62b45ba912f14ce44b832b46a
 f280015x/source/stl_util.c 2309934d20ae1759419fa96635fa1330

F28002x SDL v5.00.01
 f28002x/include/stl_can_ram.h 6e681258023830d2862feb356f056fd5
 f28002x/include/stl_cpu_reg.h ebd4a64d2c9e0e9de18d61c7e9966086
 f28002x/include/stl_crc.h a97561fa820eb9a4169bb2f0797e832b
 f28002x/include/stl_hwbist.h 0807cd39b0b5d25711f91aab24af1e13
 f28002x/include/stl_march.h 06579517c81f292238d77d17e0647b40
 f28002x/include/stl_osc_ct.h cca19730f28f9a68a003f048797961ea
 f28002x/include/stl_osc_hr.h ada6a5c5bc6e2f22db8e7853dde772e5
 f28002x/include/stl_pie_ram.h e5ee92e7da75bc79baa91e1f5bc53adf
 f28002x/include/stl_util.h 21f70b2e5f2e0441004cdb2fe3319316
 f28002x/source/stl_can_ram.c 10d1d759e590dce8ed6fe434b5247799
 f28002x/source/stl_cpu_reg.asm 14d8a30965a8aa1eee42cd6f8b5cd7a7
 f28002x/source/stl_crc.c 4e83e790250e43b89b0690c06b72d8fb
 f28002x/source/stl_crc_s.asm 296920111a7af3a9f84421f4f7c51b60
 f28002x/source/stl_hwbist.c d844aab7a19b73c283fc4ade01d3b17b
 f28002x/source/stl_hwbist_s.asm e97c2bf32ae3c56552d1b241e5670108
 f28002x/source/stl_march.c 76dff6833770cd06c2a883ab48c34ab0



f28002x/source/stl_march_s.asm	1244aad667d6f9faa4e8aa74399fe7c8
f28002x/source/stl_osc_ct.c	b78b21ed19b69e18abc0f802e73d5e12
f28002x/source/stl_osc_hr.c	b3cab1259792c3139e8ce0b66ed53a87
f28002x/source/stl_pie_ram.c	39c83574f8ee95725df58bce88675f5f
f28002x/source/stl_util.c	2309934d20ae1759419fa96635fa1330

F28004x SDL v5.00.01

f28004x/include/stl_can_ram.h	6e681258023830d2862feb356f056fd5
f28004x/include/stl_cpu_reg.h	a43d1c32f0e197ad768bc785eaf575c7
f28004x/include/stl_crc.h	a97561fa820eb9a4169bb2f0797e832b
f28004x/include/stl_march.h	06579517c81f292238d77d17e0647b40
f28004x/include/stl_osc_ct.h	cca19730f28f9a68a003f048797961ea
f28004x/include/stl_osc_hr.h	760ab4d812174f89005faebaba33169d
f28004x/include/stl_pie_ram.h	e5ee92e7da75bc79baa91e1f5bc53adf
f28004x/include/stl_util.h	a2dddef681fb81de7bee1c0bb441f321
f28004x/source/stl_can_ram.c	10d1d759e590dce8ed6fe434b5247799
f28004x/source/stl_cpu_reg.asm	1777488c31e13f089c058a02cf826375
f28004x/source/stl_crc.c	4e83e790250e43b89b0690c06b72d8fb
f28004x/source/stl_crc_s.asm	296920111a7af3a9f84421f4f7c51b60
f28004x/source/stl_march.c	76dff6833770cd06c2a883ab48c34ab0
f28004x/source/stl_march_s.asm	1244aad667d6f9faa4e8aa74399fe7c8
f28004x/source/stl_osc_ct.c	b78b21ed19b69e18abc0f802e73d5e12
f28004x/source/stl_osc_hr.c	b3cab1259792c3139e8ce0b66ed53a87
f28004x/source/stl_pie_ram.c	39c83574f8ee95725df58bce88675f5f
f28004x/source/stl_util.c	2309934d20ae1759419fa96635fa1330

F2838x SDL v5.00.01

f2838x/include/stl_can_ram.h	6e681258023830d2862feb356f056fd5
f2838x/include/stl_cpu_reg.h	ebd4a64d2c9e0e9de18d61c7e9966086
f2838x/include/stl_crc.h	a97561fa820eb9a4169bb2f0797e832b
f2838x/include/stl_hwbist.h	e563bf3082b636bec998ab561711a8d3
f2838x/include/stl_march.h	06579517c81f292238d77d17e0647b40
f2838x/include/stl_mcan_ram.h	199e0bba3430499fd346a9853982113a
f2838x/include/stl_osc_ct.h	cca19730f28f9a68a003f048797961ea
f2838x/include/stl_osc_hr.h	ada6a5c5bc6e2f22db8e7853dde772e5
f2838x/include/stl_pie_ram.h	e5ee92e7da75bc79baa91e1f5bc53adf
f2838x/include/stl_util.h	6583d8ef783f542ed0e6b38b820e7b06
f2838x/source/stl_can_ram.c	10d1d759e590dce8ed6fe434b5247799
f2838x/source/stl_cpu_reg.asm	b1b2963cc225693c99792d3d9c5b328e
f2838x/source/stl_crc.c	4e83e790250e43b89b0690c06b72d8fb
f2838x/source/stl_crc_s.asm	296920111a7af3a9f84421f4f7c51b60
f2838x/source/stl_hwbist.c	0ee9aa55bed7482e1a338d45900ee5bc
f2838x/source/stl_hwbist_s.asm	ca13567d6facf3f5dc0ef54ee7d6dec9
f2838x/source/stl_march.c	76dff6833770cd06c2a883ab48c34ab0
f2838x/source/stl_march_s.asm	1244aad667d6f9faa4e8aa74399fe7c8
f2838x/source/stl_mcan_ram.c	6c4585e2a434f76e0b949283c4680982
f2838x/source/stl_osc_ct.c	b78b21ed19b69e18abc0f802e73d5e12
f2838x/source/stl_osc_hr.c	b3cab1259792c3139e8ce0b66ed53a87
f2838x/source/stl_pie_ram.c	39c83574f8ee95725df58bce88675f5f
f2838x/source/stl_util.c	2309934d20ae1759419fa96635fa1330

F28003x SDL v5.00.01

f28003x/include/stl_can_ram.h	6e681258023830d2862feb356f056fd5
f28003x/include/stl_cpu_reg.h	ebd4a64d2c9e0e9de18d61c7e9966086
f28003x/include/stl_crc.h	a97561fa820eb9a4169bb2f0797e832b
f28003x/include/stl_hwbist.h	0807cd39b0b5d25711f91aab24af1e13
f28003x/include/stl_march.h	06579517c81f292238d77d17e0647b40
f28003x/include/stl_mcan_ram.h	078d005231a73312d834c58f88365f9e
f28003x/include/stl_osc_ct.h	cca19730f28f9a68a003f048797961ea
f28003x/include/stl_osc_hr.h	ada6a5c5bc6e2f22db8e7853dde772e5
f28003x/include/stl_pie_ram.h	e5ee92e7da75bc79baa91e1f5bc53adf
f28003x/include/stl_util.h	f470264a026d0fb4b34505ab230456b2
f28003x/source/stl_can_ram.c	10d1d759e590dce8ed6fe434b5247799
f28003x/source/stl_cpu_reg.asm	14d8a30965a8aa1eee42cd6f8b5cd7a7
f28003x/source/stl_crc.c	4e83e790250e43b89b0690c06b72d8fb
f28003x/source/stl_crc_s.asm	296920111a7af3a9f84421f4f7c51b60

f28003x/source/stl_hwbist.c	d844aab7a19b73c283fc4ade01d3b17b
f28003x/source/stl_hwbist_s.asm	e97c2bf32ae3c56552d1b241e5670108
f28003x/source/stl_march.c	76dff6833770cd06c2a883ab48c34ab0
f28003x/source/stl_march_s.asm	1244aad667d6f9faa4e8aa74399fe7c8
f28003x/source/stl_mcan_ram.c	6c4585e2a434f76e0b949283c4680982
f28003x/source/stl_osc_ct.c	b78b21ed19b69e18abc0f802e73d5e12
f28003x/source/stl_osc_hr.c	b3cab1259792c3139e8ce0b66ed53a87
f28003x/source/stl_pie_ram.c	39c83574f8ee95725df58bce88675f5f
f28003x/source/stl_util.c	2309934d20ae1759419fa96635fa1330

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f28p65x/include/stl_can_ram.h	6e681258023830d2862feb356f056fd5
f28p65x/include/stl_cpu_reg.h	ebd4a64d2c9e0e9de18d61c7e9966086
f28p65x/include/stl_crc.h	a97561fa820eb9a4169bb2f0797e832b
f28p65x/include/stl_hwbist.h	8e034989f42fbc99112b27e480a6e018
f28p65x/include/stl_lcm.h	72a01fb20d2c66903fc4457d4698bea1
f28p65x/include/stl_march.h	06579517c81f292238d77d17e0647b40
f28p65x/include/stl_mcan_ram.h	3c9ddc95d7337aa162e176f7f036306a
f28p65x/include/stl_osc_ct.h	cca19730f28f9a68a003f048797961ea
f28p65x/include/stl_osc_hr.h	ada6a5c5bc6e2f22db8e7853dde772e5
f28p65x/include/stl_pie_ram.h	e5ee92e7da75bc79baa91e1f5bc53adf
f28p65x/include/stl_util.h	eb7b70020ca97d0b7fc16e073cf9cc47
f28p65x/source/stl_can_ram.c	10d1d759e590dce8ed6fe434b5247799
f28p65x/source/stl_cpu_reg.asm	b1b2963cc225693c99792d3d9c5b328e
f28p65x/source/stl_crc.c	4e83e790250e43b89b0690c06b72d8fb
f28p65x/source/stl_crc_s.asm	296920111a7af3a9f84421f4f7c51b60
f28p65x/source/stl_hwbist.c	e740f338c0e69c28792f0b569c2148c2
f28p65x/source/stl_hwbist_s.asm	ca13567d6facf3f5dc0ef54ee7d6dec9
f28p65x/source/stl_lcm.c	a1e2e85134b48b93bc3cde057c371041
f28p65x/source/stl_march.c	76dff6833770cd06c2a883ab48c34ab0
f28p65x/source/stl_march_s.asm	1244aad667d6f9faa4e8aa74399fe7c8
f28p65x/source/stl_mcan_ram.c	9924a3243b8d5478a0bb48c656f56a13
f28p65x/source/stl_osc_ct.c	b78b21ed19b69e18abc0f802e73d5e12
f28p65x/source/stl_osc_hr.c	b3cab1259792c3139e8ce0b66ed53a87
f28p65x/source/stl_pie_ram.c	39c83574f8ee95725df58bce88675f5f
f28p65x/source/stl_util.c	2309934d20ae1759419fa96635fa1330

F28P55x SDL v5.00.01

f28p55x/include/stl_cpu_reg.h	ebd4a64d2c9e0e9de18d61c7e9966086
f28p55x/include/stl_crc.h	a97561fa820eb9a4169bb2f0797e832b
f28p55x/include/stl_march.h	06579517c81f292238d77d17e0647b40
f28p55x/include/stl_mcan_ram.h	3c9ddc95d7337aa162e176f7f036306a
f28p55x/include/stl_osc_ct.h	cca19730f28f9a68a003f048797961ea
f28p55x/include/stl_osc_hr.h	ada6a5c5bc6e2f22db8e7853dde772e5
f28p55x/include/stl_pie_ram.h	55a8311ec0c3bcfc1396303f46366d82
f28p55x/include/stl_util.h	a72075fef2d6277d527b86365fa69797
f28p55x/source/stl_cpu_reg.asm	14d8a30965a8aa1eee42cd6f8b5cd7a7
f28p55x/source/stl_crc.c	4e83e790250e43b89b0690c06b72d8fb
f28p55x/source/stl_crc_s.asm	296920111a7af3a9f84421f4f7c51b60
f28p55x/source/stl_march.c	76dff6833770cd06c2a883ab48c34ab0
f28p55x/source/stl_march_s.asm	1244aad667d6f9faa4e8aa74399fe7c8
f28p55x/source/stl_mcan_ram.c	9924a3243b8d5478a0bb48c656f56a13
f28p55x/source/stl_osc_ct.c	b78b21ed19b69e18abc0f802e73d5e12
f28p55x/source/stl_osc_hr.c	b3cab1259792c3139e8ce0b66ed53a87
f28p55x/source/stl_pie_ram.c	7e09c3816df19d81d7e90e839c9ea21f
f28p55x/source/stl_util.c	2309934d20ae1759419fa96635fa1330

Best regards

VDE Testing- and Certification Institute

Ralf Schwab



Korkut Tas



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